MEMS

CAPABILITIES

MEMS packages are qualified and in high volume production at two sites:

- Unisem Chengdu:
  LGA-FL, DTPP, LGA-ML, LGA-MC and LGA/BGA
- Unisem Batam:
  LGA-FL, LGA-MC, LGA/BGA and SOIC
- Installed total capacity of over 30 million units per month and expanding

Package Options:

- Multi die / Stacked die
- Wirebond / Flip chip
- SMT / Si / Embedded passives
- Top / Bottom Port
- Molded Cavity
- Glob top / Die Coat
- Solder Lid Attach
- Tape Assisted Molding

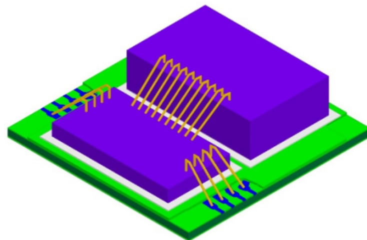
APPLICATIONS

Pressure sensors:

- Microphone
- Altimeter - barometer - BAP - humidity - GPS
- Impact detection - TMAP - Tyre Pressure Monitoring (TPMS)

Inertial sensors:

- Accelerometer
- Gyroscope



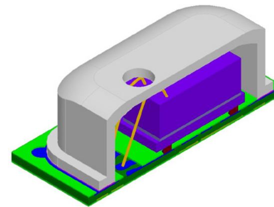
Combo's:

- Accelerometer - gyroscope - pressure humidity - ASIC - passives

KEY PACKAGES

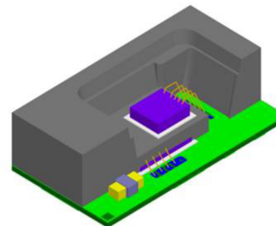
LGA-FL: LGA Formed Lid Package

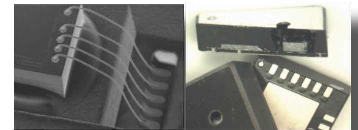
Laminate substrate package with a stamped metal lid



LGA-MC: LGA Molded Cavity Package

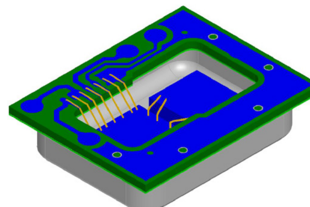
Laminate substrate molded cavity package with a flat metal, plastic or glass lid

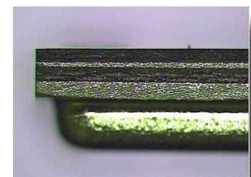




LGA-FL Direct Top Port Package

- High performance MEMS microphones
- Improved SNR
- Improved EMI shielding
- Improved Mechanical Strength
- Patented package construction





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